



Middle Tg, Lead Free & Halogen Free EM-370(5) / EM-37B(5)

- Superior thermal resistance for lead-free process
- Halogen, antimony and red phosphorus free
- For LCD, memory module and mobile device application

Basic Laminate Property

Item	IPC-TM-650	Test Condition	Unit	Typical Value	
Glass Transition Temp.	2.4.25	DSC	°C	155	
CTE, X-, Y-axis	2.4.24	Pre-Tg, TMA	ppm/°C	12/15	
CTE, Z-axis	2.4.24	Alpha 1, TMA	ppm/°C	40	
		Alpha 2, TMA	ppm/°C	190	
Z-axis Expansion	2.4.24	50~260°C, TMA	%	2.60	
Decomposition Temp.	2.4.24.26	TGA	°C	385	
Thermal Stress 10sec 288°C	2.4.13.1	Clad	—	Pass Visual	
		Etched	—	Pass Visual	
Water Absorption	2.6.2.1	E-1/105 + D-24/23	%	0.11	
Peel Strength	0.5 oz	2.4.8	As Received	lb/in	7.4
			After Thermal Stress	lb/in	7.4
	1.0 oz	2.4.8	As Received	lb/in	8.6
			After Thermal Stress	lb/in	8.4
Permittivity (RC 50%)	1 MHz	2.5.5.9	C-24/23/50	—	4.8
				1 GHz	—
Loss Tangent (RC 50%)	1 MHz	2.5.5.9	C-24/23/50	—	0.009
	1 GHz			—	0.013
Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	>10 ¹⁰	
Surface Resistivity	2.5.17.1	C-96/35/90	MΩ	>10 ⁹	
Flexural Strength	Warp	2.4.4	As Received	MPa	560~600
	Fill		As Received	MPa	470~510
Flame Resistance	UL-94	A & E-24/125	—	V-0	

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